2SB1011

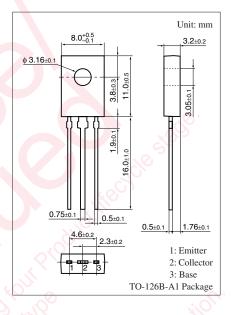
Silicon PNP triple diffusion planar type

For low-frequency output amplification

Features

- High collector-base voltage (Emitter open) V_{CBO}
- High collector-emitter voltage (Base open) V_{CEO}
- \bullet Large collector power dissipation P_{C}
- \bullet Low collector-emitter saturation voltage $V_{\mbox{CE(sat)}}$

Absolute Maximum Ratings $T_a = 25^{\circ}C$ Parameter Symbol Rating Unit Collector-base voltage (Emitter open) -400V V_{CBO} Collector-emitter voltage (Base open) VCEO -400V V Emitter-base voltage (Collector open) -5 V_{EBO} -100mA Collector current IC Peak collector current -200 I_{CP} mA 1.2 W Collector power dissipation P_{C} 150 °C Junction temperature Ti -55 to +150 °C Storage temperature T_{stg}

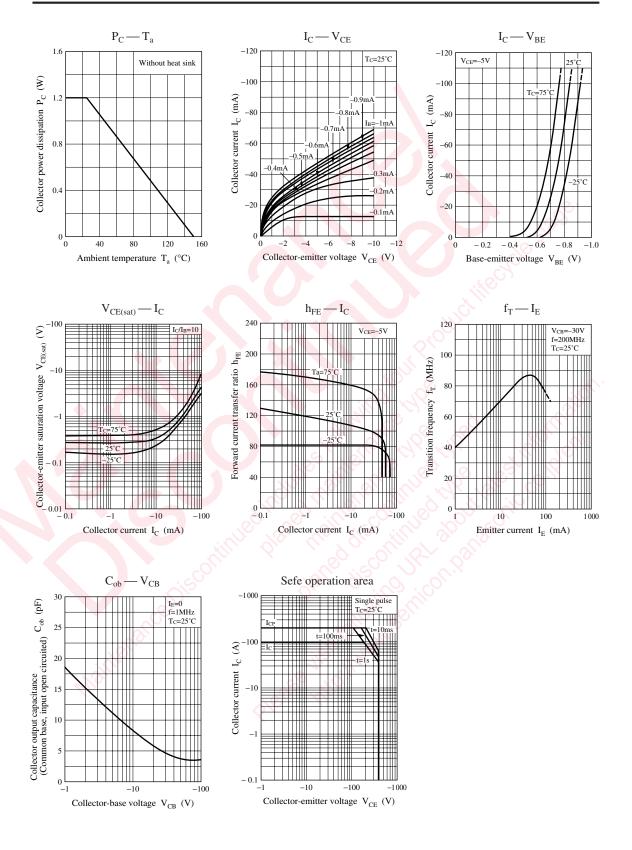


Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

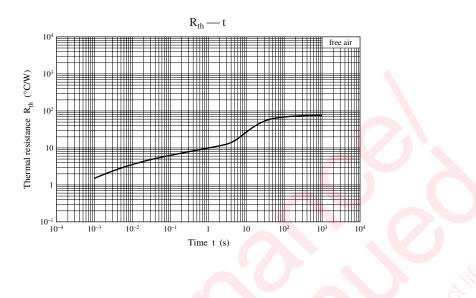
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emiter open)	V _{CBO}	$I_{\rm C} = -100 \ \mu A, \ I_{\rm E} = 0$	-400			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -500 \ \mu \text{A}, \ I_{\rm B} = 0$	-400			V
Emiter-base voltage (Collector open)	V _{EBO}	$I_E = -100 \ \mu A, I_C = 0$	-5			V
Forward current transfer ratio	h _{FE}	$V_{CE} = -5 \text{ V}, I_C = -30 \text{ mA}$	30			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -50 \text{ mA}, I_{\rm B} = -5 \text{ mA}$			-2.5	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_{\rm C} = -50 \text{ mA}, I_{\rm B} = -5 \text{ mA}$			-1.5	V
Transition frequency	f _T	$V_{CB} = -30 \text{ V}, I_E = 20 \text{ mA}, f = 200 \text{ MHz}$		70		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -30 \text{ V}, I_E = 0, f = 1 \text{ MHz}$			9	pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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